

# SOT841-1

plastic thermal enhanced thin quad flat package; 80 leads;  
body 12 x 12 x 1 mm; exposed die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HTQFP80
<b>Package type industry code</b>	HTQFP80
<b>Package style descriptive code</b>	HTQFP (thermal enhanced thin quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MS-026
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	15-1-2004

Table 1. Package summary

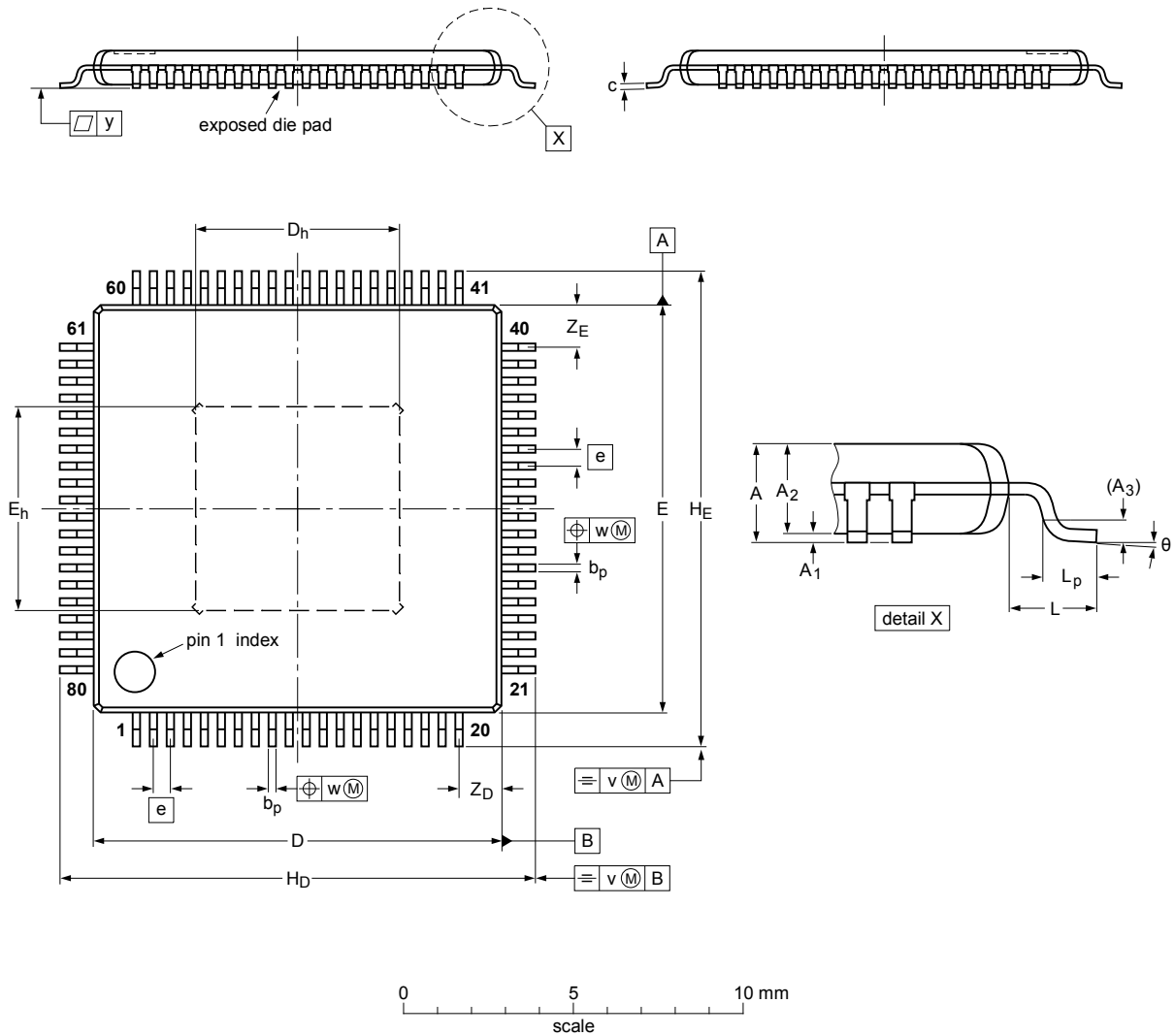
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	11.9	-	12	12.1	mm
E	package width	11.9	-	12	12.1	mm
A	seated height	[tbd]	-	1.2	1.2	mm
A <sub>2</sub>	package height	0.95	-	1	1.05	mm
n <sub>2</sub>	actual quantity of termination	-	-	80	-	



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## 2. Package outline

HTQFP80: plastic thermal enhanced thin quad flat package; 80 leads; body 12 x 12 x 1 mm; exposed die pad SOT841-1



**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	1.2	0.15 0.05	1.05 0.95	0.25	0.27 0.17	0.20 0.09	12.1 11.9	6.05 5.95	12.1 11.9	6.05 5.95	0.5	14.15 13.85	14.15 13.85	1	0.75 0.45	0.2	0.08	0.1	1.45 1.05	1.45 1.05	7° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT841-1		MS-026				04-01-15

**Fig. 1. Package outline HTQFP80 (SOT841-1)**

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### 3. Soldering

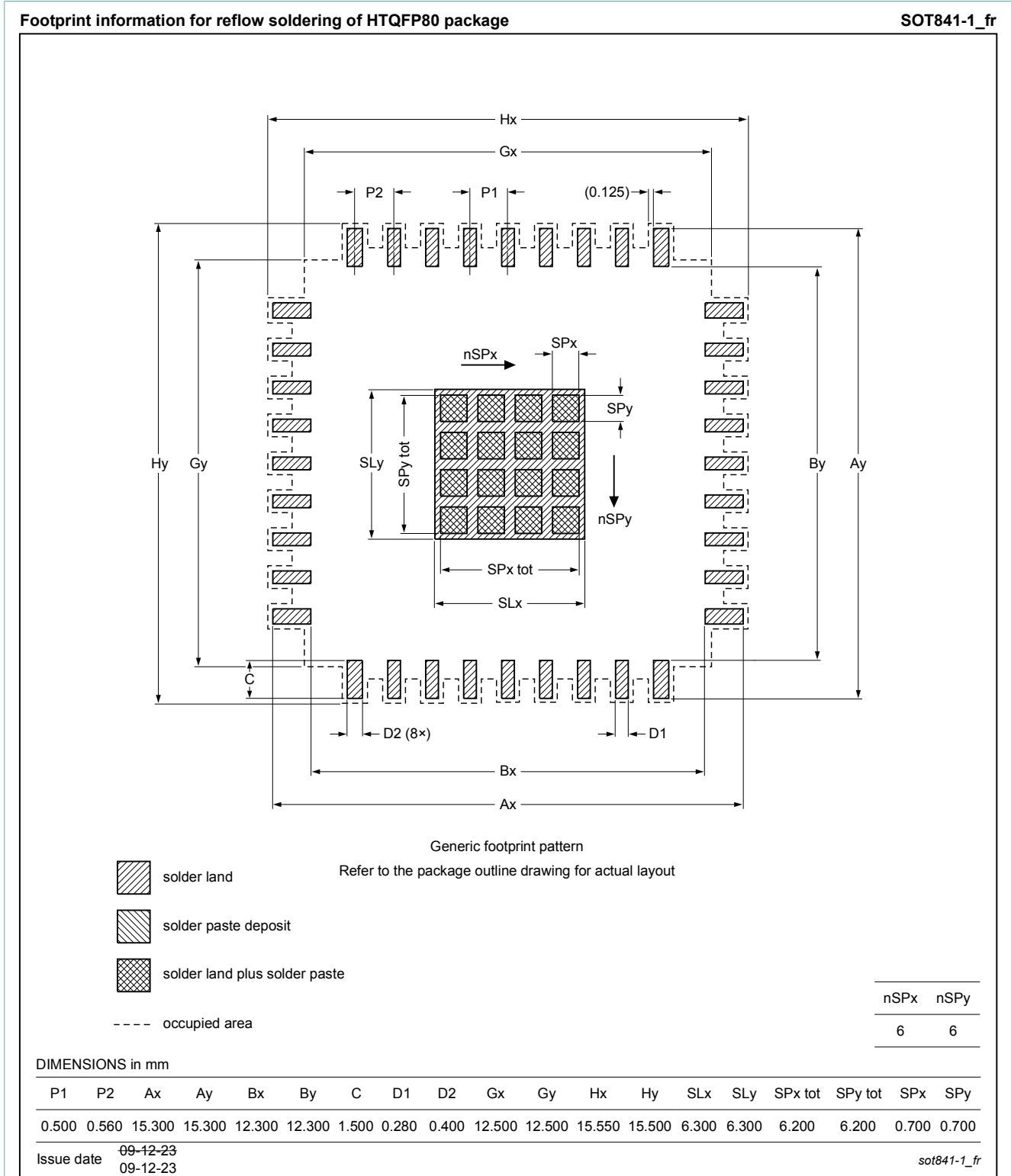


Fig. 2. Reflow soldering footprint for HTQFP80 (SOT841-1)

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## 4. Legal information

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